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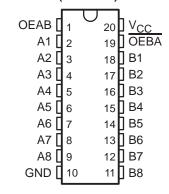
- State-of-the-Art *EPIC-IIB™* BiCMOS Design Significantly Reduces Power Dissipation
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per **JESD 17**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$
- High-Drive Outputs (-32-mA IOH, 64-mA IOI)
- **Package Options Include Plastic** Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Plastic (N) and Ceramic (J) DIPs

description

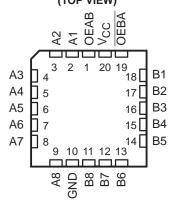
These octal bus transceivers provide for asynchronous communication between data buses. The control-function implementation allows for maximum flexibility in timing. The 'ABT620 devices provide inverted data at the outputs.

These devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic levels at the output-enable (OEAB and OEBA) inputs.

SN54ABT620 . . . J PACKAGE SN74ABT620...DB, DW, N, OR PW PACKAGE (TOP VIEW)



SN54ABT620 . . . FK PACKAGE (TOP VIEW)



The output-enable inputs can be used to disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability of storing data by simultaneously enabling OEAB and OEBA. When both OEAB and OEBA are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (16 total) remain at their last states. In this way, each output reinforces its input in this configuration.

To ensure the high-impedance state during power up or power down, OEBA should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN54ABT620 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT620 is characterized for operation from -40°C to 85°C.



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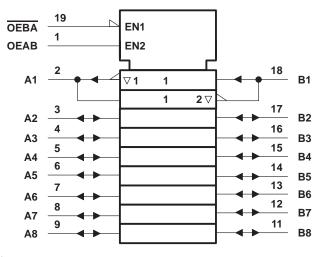
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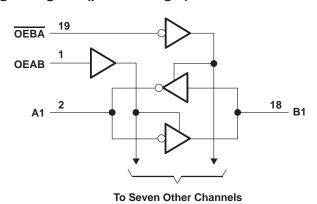
FUNCTION TABLE

INP	UTS	OPERATION
OEBA	OEAB	OPERATION
L	L	B data to A bus
L	Н	B data to A bus, A data to B bus
Н	L	Isolation
Н	Н	A data to B bus

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or	power-off state, V _O –0.5 V to 5.5 V
Current into any output in the low state, IO: SN54	4ABT620 96 mA
SN74	4ABT620 128 mA
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	
Package thermal impedance, θ _{JA} (see Note 2): D	DB package 115°C/W
D	DW package 97°C/W
N	I package 67°C/W
P	PW package 128°C/W
Storage temperature range, T _{stq}	

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



^{2.} The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

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recommended operating conditions (see Note 3)

			SN54A	BT620	SN74A	BT620	UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	EW	2		V
VIL	Low-level input voltage		0.8		0.8	V	
VI	Input voltage		0 <	Vcc	0	VCC	V
IOH	High-level output current		, ()	-24		-32	mA
loL	Low-level output current		200	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	A.	5		5	ns/V
TA	Operating free-air temperature		<i>–</i> 55	125	-40	85	°C

NOTE 3: All unused pins (control or I/O) of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54ABT620, SN74ABT620 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAI	DAMETED	TEST CON	IDITIONS	Т	A = 25°C	;	SN54A	BT620	SN74A	BT620	UNIT	
PAI	RAMETER	TEST CON	CMOITIUIS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII	
VIK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
\/~		$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3		3		V	
VOH		V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2					
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2			
V		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V	
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	v	
V _{hys}					100						mV	
	Control inputs	V _{CC} = 5.5 V,	VI = VCC or GND			±1		±1		±1	μΑ	
l _l	A or B ports $VCC = 5.5 \text{ V},$		AL = ACC OLGIAD			±100		±100		±100	μΑ	
lozh [‡]		$V_{CC} = 5.5 \text{ V},$	V _O = 2.7 V			50		50		50	μΑ	
l _{OZL} ‡		$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V			-50		– 50		-50	μΑ	
I _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100	1	ζ		±100	μΑ	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50	2700	50		50	μΑ	
IO§		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	– 50	-180	-50	-180	mA	
		V _{CC} = 5.5 V,	Outputs high		5	250		250		250	μΑ	
Icc	A or B ports	$I_0 = 0$,	Outputs low		24	30		30		30	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled		0.5	250		250		250	μΑ	
	Doto inputo	V _{CC} = 5.5 V, One input at 3.4 V,	Outputs enabled			1.5		1.5		1.5		
ΔICC¶	Data inputs	Other inputs at V _{CC} or GND	Outputs disabled			0.05		0.05		0.05	mA	
	Control inputs	$V_{CC} = 5.5 \text{ V}$, One inpute of the original of the contraction o				1.5		1.5		1.5		
Ci	Control inputs	V _I = 2.5 V or 0.5 V			4						pF	
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V			7						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

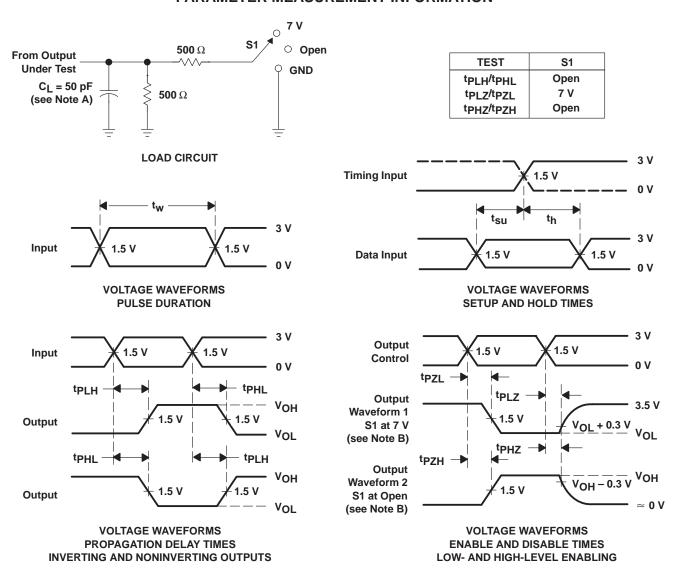
[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C		SN54ABT620		SN74A	UNIT	
	(IIVI O1)	(0011 01)	MIN	MAX	MIN	MAX	MIN	MAX	
^t PLH	A or B	B or A	1	4.1	1		1	4.8	ns
^t PHL	AOIB	D OF A	1	4.3	1	4	1	4.8	115
^t PZH	OFD.	А	1.3	4.6	1.3	1/2	1.3	5.5	ns
^t PZL	OEBA	^	1	6.1	1	2	1	7.1	115
^t PHZ	OFD.	۸	2	6.3	2	ζ	2	7	20
^t PLZ	OEBA	A	1.4	5.4	1.4		1.4	5.8	ns
^t PZH	OFAR	В	1.6	6.2	1 .6		1.6	6.8	
^t PZL	OEAB	Б	2	5.9	2		2	6.4	ns
^t PHZ	OFAR	В	1.2	5.6	1.2		1.2	6.5	
t _{PLZ}	OEAB	D	1.1	4.7	1.1		1.1	5.6	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ABT620DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT620	Samples
SN74ABT620N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74ABT620N	Samples
SN74ABT620NSR	ACTIVE	SOP	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT620	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT620NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
Γ	SN74ABT620NSR	SOP	NS	20	2000	367.0	367.0	45.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ABT620DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74ABT620N	N	PDIP	20	20	506	13.97	11230	4.32

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